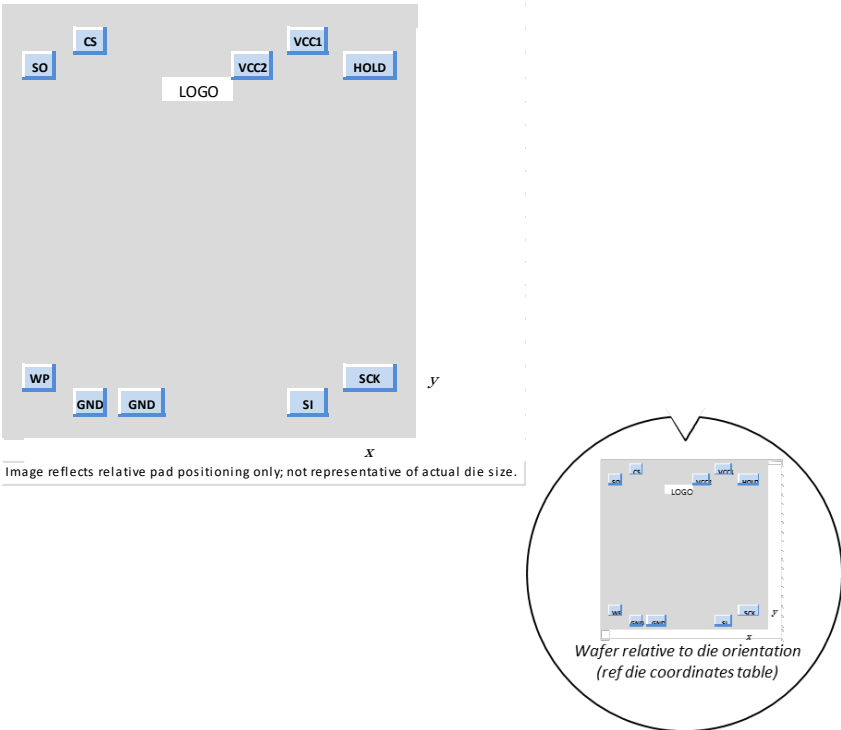


WAFER PRODUCT DATASHEET (ADDENDUM)

Product	AT25SF161-DWF																																														
Description	16Mbit, Standard Serial Flash, 2.5V – 3.6V VCC																																														
Die Map	 <p>Image reflects relative pad positioning only; not representative of actual die size.</p> <p>Wafer relative to die orientation (ref die coordinates table)</p>																																														
Die Size & Pad Coordinates	<table border="1"> <thead> <tr> <th></th> <th>X (μm)</th> <th>Y (μm)</th> </tr> </thead> <tbody> <tr> <td>Die Size</td> <td>1326</td> <td>2317</td> </tr> <tr> <td>Scribe Line Width</td> <td>80</td> <td>80</td> </tr> <tr> <td>Die Step</td> <td>1406</td> <td>2397</td> </tr> <tr> <td>Pad Opening</td> <td>65</td> <td>70</td> </tr> <tr> <td>CS</td> <td>225.9</td> <td>2253.7</td> </tr> <tr> <td>SO</td> <td>84.7</td> <td>2228.1</td> </tr> <tr> <td>WP</td> <td>62.2</td> <td>90.3</td> </tr> <tr> <td>GND</td> <td>147.2</td> <td>67.7</td> </tr> <tr> <td>GND</td> <td>232.2</td> <td>67.7</td> </tr> <tr> <td>SI</td> <td>1126.4</td> <td>64.3</td> </tr> <tr> <td>SCK</td> <td>1249.9</td> <td>90.3</td> </tr> <tr> <td>HOLD</td> <td>1243.5</td> <td>2230</td> </tr> <tr> <td>VCC1</td> <td>1144.3</td> <td>2253.7</td> </tr> <tr> <td>VCC2</td> <td>1054.3</td> <td>2232.1</td> </tr> </tbody> </table>			X (μm)	Y (μm)	Die Size	1326	2317	Scribe Line Width	80	80	Die Step	1406	2397	Pad Opening	65	70	CS	225.9	2253.7	SO	84.7	2228.1	WP	62.2	90.3	GND	147.2	67.7	GND	232.2	67.7	SI	1126.4	64.3	SCK	1249.9	90.3	HOLD	1243.5	2230	VCC1	1144.3	2253.7	VCC2	1054.3	2232.1
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Technical Details	
Adesto Product Family	Standard Flash
Density	16 Mbit
Operating Vcc	2.5V - 3.6V
ESD	JESD22-A114
Delivery Option	Wafer- unsawn
Wafer Size (mm)	300 mm
Process Geometry (nm)	90 nm
Die ID	5187
Wafer Map	Electronic- text file
Manufacturing Facility	XMC
Wafer Thickness (µm) Maximum	800
Back Grind Options	None / Contact Adesto
Back Plane Connection	Floating / Not Required
Backside preparation / metallization	None
Bond wire qualified	AU <input checked="" type="checkbox"/> CU <input type="checkbox"/> AG <input type="checkbox"/>
Passivation Material	PETEOS + SiON
Passivation Thickness (Å)	11000
Bond Pad Material	TaN/AlCu
Bond Pad Thickness (Å)	10300
Good Die per Wafer	Contact Adesto (AT25SF161-DWF) ¹
Active Circuits underneath the bond pad	Yes

¹ Average value; subject to change without notice.

Part Number Ordering Code ²	Operating Temperature Range	Functional Specification
AT25SF161-DWF	-40°C to 85°C	http://www.adestotech.com/wp-content/uploads/DS-AT25SF161_046.pdf

² Handle product in accordance with UV and ESD precautions.

Revision Level – Release Date	History
A – September 2015	Initial release.
B – August 2017	Updated address and contact information.

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